

Material Declaration Report



Package Type:	TDFN 16L
Pericom Package Code:	ZJ16(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	11.747
Termination Plating:	NiPdAu
JESD 97 Pb-free Category:	e4
Plating Thickness (um):	0.5~2.2
Tin Whisker Mitigation:	N/A

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	40
Reflow Cycles:	3
Rev Date:	7/1/2008

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	7.088	UTL	Silica fuse	60676-86-0	90.500	6.4146
			Epoxy resin	Proprietary	4.500	0.3190
			Phenol resin	Proprietary	4.500	0.3190
			Carbon black	1333-86-4	0.500	0.0354
LEADFRAME	4.258		Copper	7440-50-8	96.953	4.1283
			Iron	7439-89-6	2.350	0.1001
			Zinc	7440-66-6	0.111	0.0047
			Phosphorus	7723-14-0	0.065	0.0028
			Nickel	7440-02-0	0.473	0.0201
			Palladium	7440-05-3	0.041	0.0017
			Gold	7440-57-5	0.007	0.0003
SILICON DIE	0.170		Silicon (Si)	7440-21-3	99.192	0.1686
			Non-hazardous Metal	Proprietary	0.808	0.0014
DIE ATTACH EPOXY	0.073		Treated silica	129915-35-1	35.000	0.0256
			Glycol ethers	Proprietary	32.000	0.0234
			Metal oxide	Proprietary	22.000	0.0161
			Curing agent & hardener	Proprietary	8.000	0.0058
			Epoxy resins	7631-86-9	3.000	0.0022
GOLD WIRE	0.158		Gold(Au)	7440-57-5	99.990	0.1580
			Impurities	-	0.010	0.0000

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

	MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Device	Mold Compound	<2	<2	<2	<2	<5	<5
	Leadframe	<50	<2	<2	<2	<5	<5
	Silicon Die	<2	<2	<2	<2	<5	<5
	Die Attach Epoxy	<2	<2	<2	<2	<5	<5
	Gold Wire	<2	<2	<2	<2	<5	<5
	Solder Plating	<2	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium																	
	<table border="1"> <thead> <tr> <th>Pb</th> <th>Hg</th> <th>Cr+6</th> <th>Cd</th> <th>PBB</th> <th>PBDE</th> </tr> </thead> <tbody> <tr> <td><1000ppm</td> <td><1000ppm</td> <td><1000ppm</td> <td><100ppm</td> <td><1000ppm</td> <td><1000ppm</td> </tr> <tr> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> </tr> </tbody> </table>	Pb	Hg	Cr+6	Cd	PBB	PBDE	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	O	O	O	O	O
Pb	Hg	Cr+6	Cd	PBB	PBDE													
<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm													
O	O	O	O	O	O													
<p>O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.</p> <p>X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.</p>																		